

SOLID TANTALUM CAPACITOR SVS SERIES

Surface mount resin molded, Ultra miniaturized chip

The SVS series is a line-up of high performance ultra miniaturized tantalum chip capacitors. The case dimensions are $2.0 \text{ mm} \times 1.25 \text{ mm} \times 1.2 \text{ mm}$ as shown below.

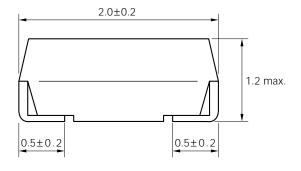
FEATURES

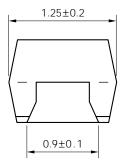
- The smallest molded chip tantalum capacitor (half size of the EIA standard A case)
- \circ Available up to 10 μ F with case dimension of 2.0 mm \times 1.25 mm \times 1.2 mm (case code P)

APPLICATIONS

- Portable stereos
- VCR cameras
- Hearing aids

DIMENSIONS





(Unit:mm)

The information in this document is subject to change without notice.

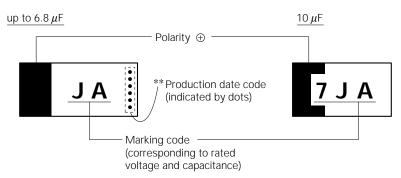


PRODUCT LINE-UP AND MARKING CODE

U _R (Vdc) Capacitance (μF)	2.5	4	6.3	10	16
0.33					CN
0.47					CS
0.68				AW	CW
1			JA	AA	CA
1.5		GE	JE	AE	
2.2	eJ	GJ	JJ	AJ	
3.3	eN	GN	JN	AN	
4.7	eS	GS	JS		
6.8	eW	GW	JW		
10	7eA	7GA	7JA		

U_R: Rated voltage

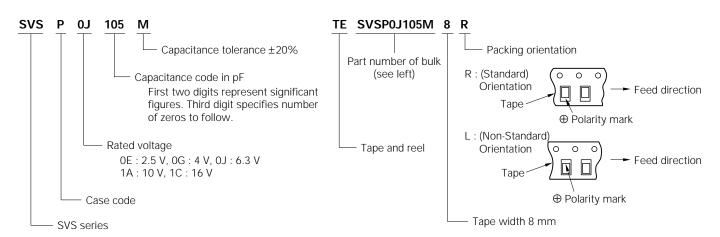
Marking detail



** Implement date code on trial.

PART NUMBER SYSTEM

[BULK] [TAPE & REEL]





RATINGS

Rated Voltage (Vdc)	Capacitance (μF)	Tangent of loss angle	Leakage Current (μΑ)	Part Number
	2.2	0.1	0.5	SVSP0E225M
	3.3	0.1	0.5	SVSP0E335M
2.5	4.7	0.2	0.5	SVSP0E475M
	6.8	0.2	0.5	SVSP0E685M
	10	0.2	0.5	SVSP0E106M
	1.5	0.1	0.5	SVSP0G155M
	2.2	0.1	0.5	SVSP0G225M
4	3.3	0.2	0.5	SVSP0G335M
4	4.7	0.2	0.5	SVSP0G475M
	6.8	0.2	0.5	SVSP0G685M
	10	0.2	0.5	SVSP0G106M
	1	0.1	0.5	SVSP0J105M
	1.5	0.1	0.5	SVSP0J155M
	2.2	0.2	0.5	SVSP0J225M
6.3	3.3	0.2	0.5	SVSP0J335M
	4.7	0.2	0.5	SVSP0J475M
	6.8	0.2	0.5	SVSP0J685M
	10	0.2	0.6	SVSP0J106M
	0.68	0.1	0.5	SVSP1A684M
	1	0.1	0.5	SVSP1A105M
10	1.5	0.2	0.5	SVSP1A155M
	2.2	0.2	0.5	SVSP0A225M
	3.3	0.2	0.5	SVSP0A335M
	0.33	0.1	0.5	SVSP1C334M
4.	0.47	0.1	0.5	SVSP1C474M
16	0.68	0.1	0.5	SVSP1C684M
	1	0.2	0.5	SVSP1C105M



SPECIFICATIONS

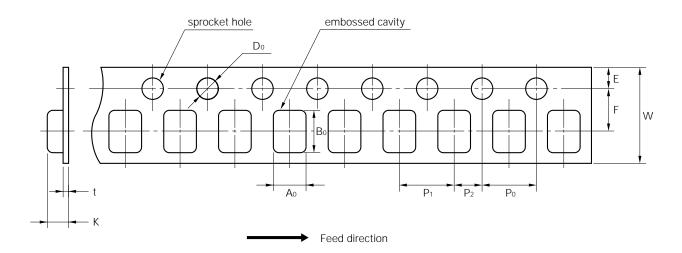
No.	Item	Specifications						Test Conditions		
1	Operating Tem	p. Range	−55 to +125°C						Over 85°C, applied voltage shall be derated on the basis of the Derated Voltage at 125°C specified in this table item no.4.	
2	Rated Voltage	2.5	4	6.3	10	16	Vdc	up to 85°C		
3	Surge Voltage		3.3	5.2	8	13	20	Vdc	up to 85°C	
4	Derated Voltag	е	1.6	2.5	4	6.3	10	Vdc	at 125°C	
5	Capacitance Ra	inge			0.33 to	10 μF			at 120 Hz	
6	Capacitance To	lerance			±20	0%			at 120 Hz	
7	Leakage Currer	nt			0.5 μΑ	max.			5 min. after rated voltage applied	
8	Tangent of loss	angle		0.1 max	/ 0.2 max	. (Refer t	o ratings)		at 25°C, 120 Hz	
9								at 85°C Surge voltage for 30 sec. (Rs = 1 k Ω) Discharge for 5 min. 30 sec. 1 000 cycles		
		Temp.	-55	°C	+85°		+125	2.C		
	Characteris-	⊿C/C	0 -20	%	+20 c	%	+20 0	%	Step1: +25°C	
10	tics at high	Tangent of loss angle	150% of requirer		Initial requiren	nent	150%of initial requirement		Step2 : -55°C Step3 : +25°C Step4 : +85°C	
	temperature	Leakage Current	_	-	0.1 CV of whichev greater	'	0.125 CV o whichever greater	•	Step5 : +125°C Step6 : +25°C	
11	Rapid change of	temperature	Tange	$_{\Delta}$ C/C : $\pm 20\%$ Tangent of loss angle : Initial requirement Leakage Current : Initial requirement			IEC68-2-14 Test N and IEC68-2-33 Guidance -55 to +125°C 5 cycles			
12	Resistance to s	oldering	△C/C : ±20% Tangent of loss angle : Initial requirement Leakage Current : Initial requirement				IEC68-2-58 Test Td Fully immersion to solder at 260°C for 5 sec			
13	Damp Heat (St	Δ C/C : $\pm 20\%$ Tangent of loss angle : 150% of Intial requirement Leakage Current : Initial requirement					IEC68-2-3 Test Ca at 40°C, 90 to 95% RH, for 500H			
14	Endurance	Tange	Δ C/C : \pm 20% Tangent of loss angle : Initial requirement Leakage Current : 200% of Initial requirement			at 85°C & 125°C (Derated Voltage), rated voltage applied for 2 000 H				
15	Failure Rate				λο = 1%	/1 000 h			at 85°C & 125°C (Derated Voltage), rated voltage applied for 1 000 H	

△C/C : Capacitance change ratio



TAPE AND REEL SPECIFICATION

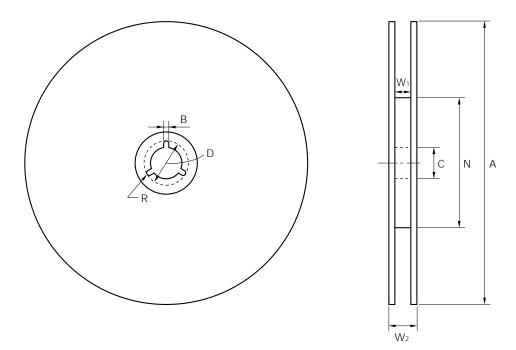
[Carrier Tape Specification and Packing Quantity]



(Unit:mm)

Ao±0.2	Bo±0.2	W±0.3	F±0.05	E±0.1	P1±0.1	P2±0.05	Po±0.1	Do +0.1	K±0.2	t	Q'ty/Reel
1.4	2.2	8.0	3.5	1.75	4.0	2.0	4.0	φ1.5	1.4	0.2	3000

[Reel Specification]



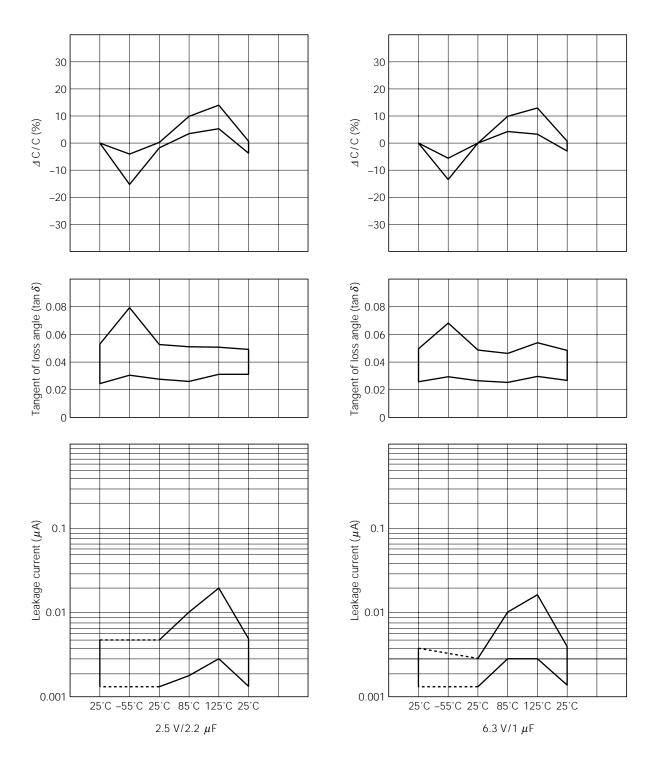
(Unit:mm)

Tape width	Α	N	С	D	В	W ₁	W ₂	R
8	φ178±2.0	ϕ 50 min.	φ13±0.5	φ21±0.5	2.0±0.5	10.0±1.0	14.5 max.	1

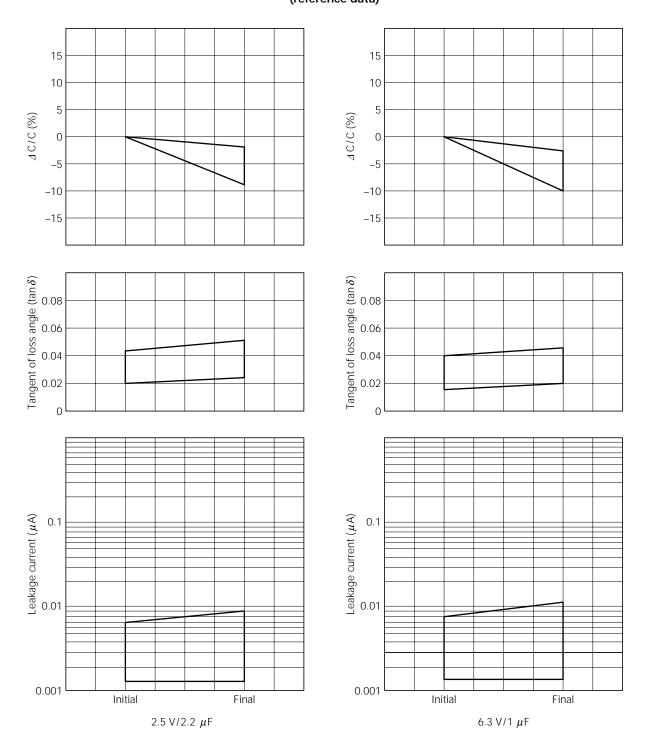


CHARACTERISTICS DATA

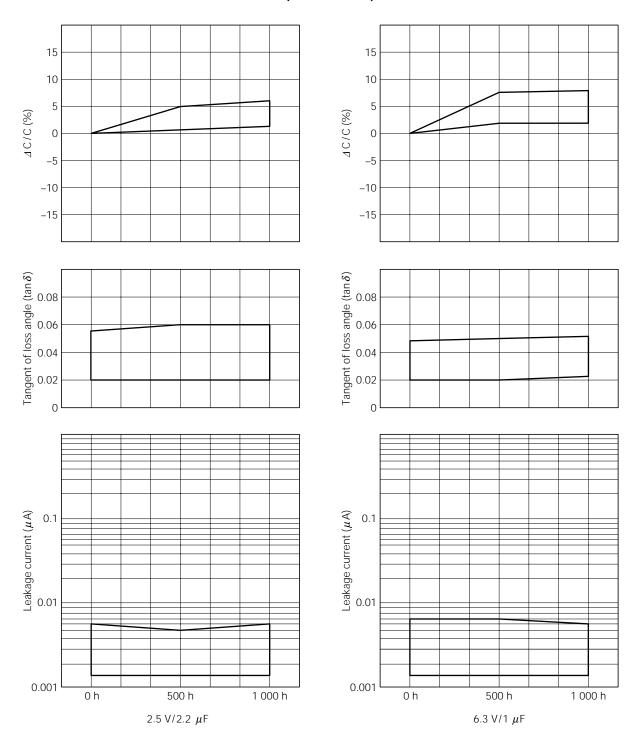
Characteristics at high and low temperature



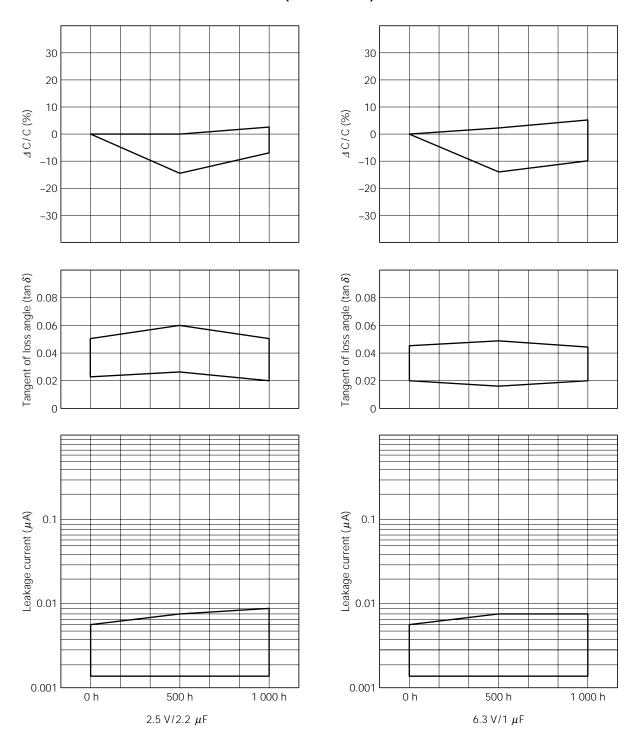
Resistance to soldering (immersing for 10 sec. at 260°C) (reference data)



Damp heat, steady state (65°C, 90 to 90% RH) (reference data)

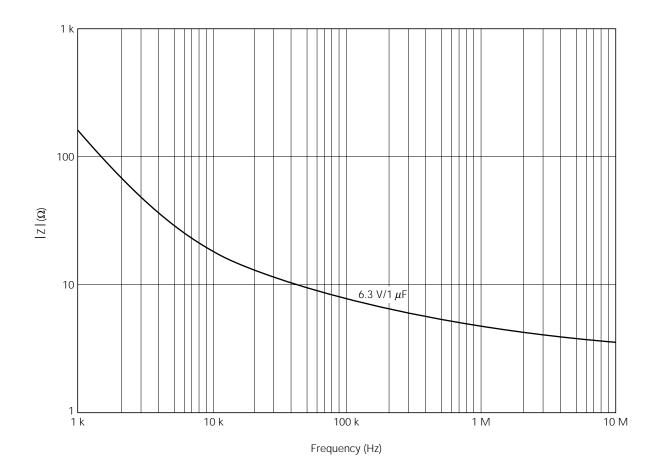


Endurance (85°C, Rated voltage \times 1.3 applied) (reference data)





Impedance – Frequency characteristics (reference data)





GUIDE TO APPLICATIONS FOR TANTALUM CHIP CAPACITORS

The failure of the solid tantalum capacitor is mostly classified into a short-circuiting mode and a large leakage current mode. Refer to the following for reliable circuit design.

1. Expecting Reliability

SVS series tantalum chip capacitors are typically applied to decoupling, blocking, bypassing and filtering.

The SVS series has a very high reliability (low failure rate) in the field. For example, the maximum field failure rate of an SVS series capacitor with a DC rated voltage of 16 V is 0.0004%/1000 hour (4 Fit) at an applied voltage of 5 V, operating temperature of 25° C and series resistance of 3 Ω .

The maximum failure rate in the field is estimated by the following expression:

$$\lambda = \lambda_0 \left(\frac{V}{V_0} \right)^3 \times 2^{\left(\frac{T - T_0}{10} \right)}$$

 λ : Maximum field failure rate

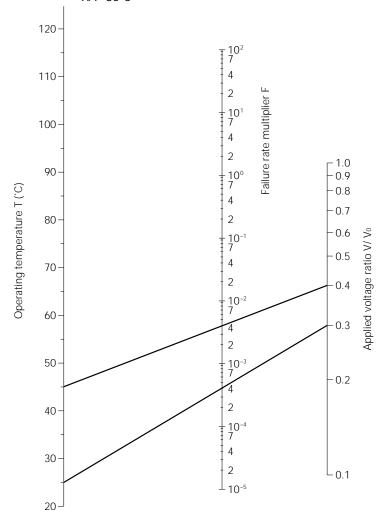
 λ_0 : 1%/1000 hour (The failure rate of the SVS series at the full DC rated voltage at operating temperature of 85°C and series resistance of 3 Ω .)

V: Applied voltage in actual use

Vo: DC Rated voltage

T: Operating temperature in actual use

To: 85°C



The nomograph is provided for quick estimation of maximum field failure rates.

Connect operating temperature T and applied voltage ratio V/V₀ of interest with a straight line. The failure rate multiplier F is given at the intersection of this line with the model scale. The failure rate is obtained as $\lambda = \lambda_0 \cdot F$.

Examples:

Given V/V₀ = 0.4 and T = 45°C. read F = 4×10^{-3} Hence, λ = 0.004%/1000 hour (40 Fit). Given V/V₀ = 0.3 and T = 25°C, read F = 4×10^{-4} Hence, λ = 0.0004%/1000 hour (4 Fit).

2. Series resistance

As shown in Figure 1, reliability is increased by inserting a series resistance of at least 3 Ω /V into circuits where current flow is momentary (switching circuits, charge/discharge circuits, etc).

If the capacitor is in a low-impedance circuit, the voltage applied to the capacitor should be less than 1/2 to 1/3 of the DC rated voltage.



Figure 1 Effects of series resistance

3. Ripple voltage

The sum of DC voltage and peak ripple voltage should not exceed the DC rated voltage of the capacitor.

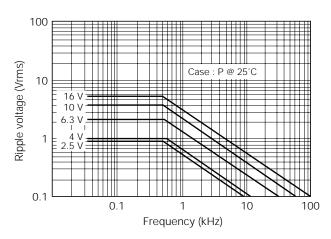


Figure 2 Permissible ripple voltage vs. frequency

Figure 2 is based on an ambient temperature of 25°C. For higher temperature, permissible ripple voltage shall be derated as follows.

Permissible voltage at $50^{\circ}\text{C} = 0.7 \times \text{permissible voltage}$ at 25°C Permissible voltage at $85^{\circ}\text{C} = 0.5 \times \text{permissible voltage}$ at 25°C Permissible voltage at $125^{\circ}\text{C} = 0.3 \times \text{permissible}$ voltage at 25°C

4. Reverse voltage

Because the capacitors are polarized, reverse voltage should not be applied.

If reverse voltage cannot be avoided because of circuit design, the voltage application should be for a very short time and should not exceed the following.

10% of DC rated voltage at 25°C5% of DC rated voltage at 85°C1% of DC rated voltage at 125°C



5. Mounting

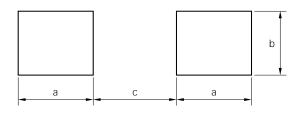
(1) Direct soldering

Keep in mind the following points when soldering the capacitor by means of jet soldering or dip soldering:

(a) Temporarily fixing resin

Because the SVS series solid tantalum capacitors are larger in size and subject to more force than the chip multilayer ceramic capacitors or chip resistors, more resin is required to temporarily secure the solid tantalum capacitors. However, if too much resin is used, the resin adhering to the patterns on a printed circuit board may adversely affect the solderability.

(b) Pattern design



Case	a	b	С
Р	2.2	1.4	0.7

The above dimensions are for reference only. If the capacitor is to be mounted by this method, and if the pattern is too small, the solderability may be degraded.

(e) Temperature and time

Keep the peak temperature and time to within the following values:

Solder temperature 260°C max.

Time 5 seconds max.

Whenever possible, perform preheating (at 150°C max.) for smooth temperature profile. To maintain the reliability, mount the capacitor at a low temperature and in a short time whenever possible.

(d) Component layout

If many types of chip components are mounted on a printed circuit board which is to be soldered by means of jet soldering, solderability may not be uniform over the entire board depending on the layout and density of the components on the board (also take into consideration generation of flux gas).

(e) Flux

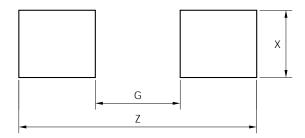
Use resin-based flux. Do not use flux with strong acidity.



(2) Reflow soldering

Keep in mind the following points when soldering the capacitor in a soldering oven or with a hot plate:

(a) Pattern design (In accordance with IEC1182)



Case	G max.	Z min.	X min.
Р	0.5	2.6	1.2

The above dimensions are recommended. Note that if the pattern is too big, the component may not be mounted in place.

(b) Temperature and time

Keep the peak temperature and time to within the following values:

Solder temperature 260°C max.

Time: 10 seconds max.

Whenever possible, perform preheating (at 150°C max.) for smooth temperature profile. To maintain the reliability, mount the capacitor at a low temperature and in a short time whenever possible. The peak temperature and time shown above are applicable when the capacitor is to be soldered in a soldering oven or with a hot plate. When the capacitor is soldered by means of infrared reflow soldering, the internal temperature of the capacitor may rise beyond the surface temperature.

(3) Using soldering iron

When soldering the capacitor with a soldering iron, controlling the temperature at the tip of the soldering iron is very difficult. However, it is recommended that the following temperature and time be observed to maintain the reliability of the capacitor:

Iron temperature300°C max.Time3 seconds max.Iron power30 W max.



6. Cleaning

Generally, several organic solvents are used for flux cleaning of an electronic component after soldering. Many cleaning methods, such as immersion cleaning, rinse cleaning, brush cleaning, shower cleaning, vapor cleaning, and ultrasonic cleaning, are available, and one of these cleaning methods may be used alone or two or more may be used in combination. The temperature of the organic solvent may vary from room temperature to several 10°C, depending on the desired effect. If cleaning is carried out with emphasis placed only on cleaning effect, however, the marking on the electronic component cleaned may be erased, the appearance of the component may be damaged, and in the worst case, the component may be functionally damaged. It is therefore recommended that the SVS series solid tantalum capacitor be cleaned under the following conditions:

[Recommended conditions of flux cleaning]

(1) Cleaning solvent Chlorosen, isopropyl alcohol

(2) Cleaning method Shower cleaning, rinse cleaning, vapor cleaning

(3) Cleaning time 5 minutes max.

* Ultrasonic cleaning

This cleaning method is extremely effective for eliminating dust that has been generated as a result of mechanical processes, but may pose a problem depending on the condition. As a result of an experiment conducted by NEC, it was confirmed that the external terminals of the capacitor were cut when it was cleaned with some ultrasonic cleaning machines. The cause of this phenomenon is considered metal fatigue of the capacitor terminals that occurred due to ultrasonic cleaning. To prevent the terminal from being cut, decreasing the output power of the ultrasonic cleaning machine or shortening the cleaning time may be a possible solution. However, it is difficult to specify the safe cleaning conditions because there are many factors involved such as the conversion efficiency of the ultrasonic oscillator, transfer efficiency of the cleaning bath, difference in cleaning effect depending on the location in the cleaning bath, the size and quantity of the printed circuit boards to be cleaned, and the securing states of the components on the boards. It is therefore recommended that ultrasonic cleaning be avoided as much as possible.

If ultrasonic cleaning is essential, make sure through experiments that no abnormality occur as a result of the cleaning. For further information, consult NEC.

7. Others

- (1) Do not apply excessive vibration and shock to the capacitor.
- (2) The solderability of the capacitor may be degraded by humidity. Store the capacitor at (-5 to +40°C) room temperature and (40 to 60% RH) humidity.
- (3) Exercise care that no external force is applied to the tape packaged products (if the packaging material is deformed, the capacitor may not be automatically mounted by a chip mounter).

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"Standard", "Special", and "Specific". The Specific quality grade applies only to devices developed based on a customer designated "quality assurance program" for a specific application. The recommended applications of a device depend on its quality grade, as indicated below. Customers must check the quality grade of each device before using it in a particular application.

Standard: Computers, office equipment, communications equipment, test and measurement equipment, audio and visual equipment, home electronic appliances, machine tools, personal electronic equipment and industrial robots Special: Transportation equipment (automobiles, trains, ships, etc.), traffic control systems, anti-disaster systems, anti-crime systems, safety equipment and medical equipment (not specifically designed for life support)

Specific: Aircrafis, aerospace equipment, submersible repeaters, nuclear reactor control systems, life support systems or medical equipment for life support, etc.

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If customers intend to use NEC devices for applications other than those specified for Standard quality grade, they should contact an NEC sales representative in advance.

Anti-radioactive design is not implemented in this product.